



Atty. Docket No.: 843.37610X00
Serial No.: 09/381,400

#15
Amend
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(NE)
8-8-02
ASB

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Yoshinori Miyaki et al.
Serial No.: 09/381,400
Filed: February 3, 2000
For: SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD
Art Unit: 2826
Examiner: Alexander O. Williams

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enter
8/13/02

AMENDMENT AFTER FINAL REJECTION UNDER 37 C.F.R. § 1.116

Assistant Commissioner of Patents
Washington, D.C. 20231

August 5, 2002

Sir:

In response to the Office Action dated April 4, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please amend claims 24, 26, 31 and 33 as follows.

B¹
24. (Amended) A semiconductor device according to claim 23, wherein an adhesion strength between a material of said organic film and a resin material of said resin body is relatively greater than an adhesion strength between a material of said inorganic film and said resin material of said resin body.

B²
26. (Amended) A semiconductor device according to claim 25, wherein said semiconductor chip is a silicon chip and said rear surface of said semiconductor chip